

LINEAR TECHNOLOGY MATERIALS DECLARATION

| 1t1211is8#trpbf                   |                                  |                           |            | (Engineering Calculation) |                               | SOIC                            |
|-----------------------------------|----------------------------------|---------------------------|------------|---------------------------|-------------------------------|---------------------------------|
| (printed on: 2020-07-11 20:05:33) |                                  |                           |            |                           | TOTAL MASS (g) : 0.075424     |                                 |
| COMPONENT MATERIAL                | VENDOR/ INDUSTRY NAMES           | CONSTITUENT NAME          | CAS NUMBER | CONSTITUENT MASS (g)      | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
| Active Device                     | Linear Technology                | Silicon (Si)              | 7440-21-3  | 0.003683                  | 1000000                       | 48830.7070312                   |
| Die Coat                          | Dow Corning                      | Silicone                  | 69430-27-9 | 0.000153                  | 1000000                       | 2028.53601074                   |
| Lead Frame                        | Cu                               | Copper (Cu)               | 7440-50-8  | 0.023653                  | 975000                        | 313601.0625                     |
|                                   |                                  | Iron (Fe)                 | 7439-89-6  | 0.000582                  | 24000                         | 7716.39208984                   |
|                                   |                                  | Phosphorus (P)            | 7723-14-0  | 0.000007                  | 300                           | 92.8088378906                   |
|                                   |                                  | Zinc (Zn)                 | 7440-66-6  | 0.000017                  | 700                           | 225.39289856                    |
|                                   |                                  | Nickel (Ni)               | 7440-02-0  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Silicon (Si)              | 7440-21-3  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Magnesium (Mg)            | 7439-95-4  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Lead Frame Total:         |            | 0.024259                  | 1000000                       | 321635.625                      |
| Plating                           | PMI                              | Exter. Plating Pb         | 7439-92-1  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Exter. Plating Sn         | 7440-31-5  | 0.001477                  | 1000000                       | 19580.703125                    |
|                                   |                                  | External Plating Total:   |            | 0.001477                  | 1000000                       | 19580.703125                    |
|                                   |                                  | Inter. Plating Ni         | 7440-02-0  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Inter. Plating Ag         | 7440-22-4  | 0.000194                  | 1000000                       | 2572.13061523                   |
|                                   |                                  | Internal Plating Total:   |            | 0.000194                  | 1000000                       | 2572.13061523                   |
| Die Attach                        | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag)               | 7440-22-4  | 0.001042                  | 750000                        | 13815.2587891                   |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Lead (Pb)                 | 7439-92-1  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Indium (In)               | 7440-74-6  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Metal Oxide               |            | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Antimony (Sb)             | 7440-36-0  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Resin (EP)                |            | 0.000347                  | 250000                        | 4600.66650391                   |
|                                   |                                  | Die Attach Total:         |            | 0.001389                  | 1000000                       | 18415.9238281                   |
| Encapsulation                     | MULTI-AROMATIC RESIN Br/Sb FREE  | Resin (EP)                |            | 0.006613                  | 150000                        | 87677.828125                    |
|                                   |                                  | Bromine (Br)              | 40039-93-8 | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.036149                  | 820000                        | 479278.09375                    |
|                                   |                                  | Antimony Trioxide (Sb2O3) | 1309-64-4  | 0.000000                  | 0                             | 0                               |
|                                   |                                  | Metal Hydroxide           |            | 0.001102                  | 25000                         | 14610.7626953                   |
|                                   |                                  | Carbon Black (C)          | 1333-86-4  | 0.000220                  | 5000                          | 2916.84912109                   |
|                                   |                                  | Encapsulation Total:      |            | 0.044084                  | 1000000                       | 584483.5625                     |
| Bond Wire Estimated               | AFW/TANAKA/ Kn                   | Gold (Au)                 | 7440-57-5  | 0.000185                  | 1000000                       | 2452.80493164                   |
|                                   |                                  |                           |            |                           | TOTAL MASS (g) :              | 0.075424                        |